



(51) International Patent Classification:

C09K 5/00 (2006.01)

(21) International Application Number:

PCT/US2017/041857

(22) International Filing Date:

13 July 2017 (13.07.2017)

(25) Filing Language:

English

(26) Publication Language:

English

(71) Applicant: **HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P.** [US/US]; 11445 Compaq Center Drive West, Houston, Texas 77070 (US).

(72) Inventors: **WU, Kuan-Ting**; 10F, No.66, Jing Mao 2 Rd., NanGang District, Taipei, 11568 (TW). **WAKIL, Jamil**; 11445 Compaq Center Dr W, Houston, Texas 77070 (US). **CASTILLO, Davis**; 11445 Compaq Center Dr W, Houston, Texas 77070 (US).

(74) Agent: **COSTALES, Shruti**; 3390 E. Harmony Road, Fort Collins, Colorado 80528 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

- as to the identity of the inventor (Rule 4.17(i))
- as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))

Published:

- with international search report (Art. 21(3))

(54) Title: COATING COMPOSITION(S)

(57) Abstract: Described herein in some examples is a heat dissipation coating composition for an electronic device, which can comprise: a transparent coating layer deposited on a surface of the electronic device, wherein the coating layer comprises: a heat absorber selected from the group consisting of silica aerogel, carbon nanotubes, carbon nanotube aerogel, graphene, graphene aerogel, and combinations thereof, a transparent resin selected from the group consisting of a polyacrylic resin, a polycarbonate resin, a cyclic olefin resin, an epoxy resin, a urethane resin, a silicone resin, a cyanoacrylate resin, a polyester resin, and combinations thereof, and a solvent; and a heat spreader layer deposited at least partially on top of the transparent coating layer or deposited on the surface of the electronic device adjacent to the transparent coating layer, wherein the heat spreader layer comprises: metallic or non-metallic particles selected from the group consisting of copper, aluminum, graphite, carbon nanotube, graphene on a metal, graphene, and combinations thereof.



5

COATING COMPOSITION(S)

BACKGROUND

10 [0001] Electronic devices such as desktop computers, laptop computers, mobile phones, handheld devices, printing devices, and other electronic devices tend to heat during use.

BRIEF DESCRIPTION OF THE DRAWINGS

15 [0002] Features of examples of the present disclosure will become apparent by reference to the following detailed description and drawings, in which like reference numerals correspond to similar, though perhaps not identical, components. For the sake of brevity, reference numerals or features having a previously described function may or may not be described in connection with other drawings in which
20 they appear.

[0003] FIG. 1 is a sectional view of an electronic device substrate coated with a heat dissipation coating composition according to an example;

[0004] FIG. 2 is a sectional view of an electronic device substrate coated with a heat dissipation coating composition according to another example;

25 [0005] FIG. 3 is a sectional view of an electronic device substrate coated with a heat dissipation coating composition according to another example;

[0006] FIG. 4 is a top view of an electronic device substrate coated with a heat dissipation coating composition according to an example;

[0007] FIG. 5 is a top view of an electronic device substrate coated with a heat
30 dissipation coating composition according to an example;

[0008] FIG. 6 is a top view of a common synthetic graphite film;

[0009] FIG. 7 is a top view of a transparent coating layer in a heat dissipation coating composition according to an example; and

[0010] FIG. 8 is a flow diagram of a method of depositing a heat dissipation coating composition on an electronic device according to an example.

DETAILED DESCRIPTION

5 [0011] Most electronic device(s) such as desktop computers, laptop computers, mobile phones, handheld devices, printing devices, and other electronic devices tend to generate heat during normal use. This generation of heat can become excessive and as a result damaging to the device due to many different reasons including dust inside the electronic device, a new component such as a hard drive
10 added to the electronic device (the extra component can cause the power supply to work harder and generate extra heat), over time some cooling fans might slow down and wear out causing a build-up of heat, and/or high ambient room temperature.

[0012] A common cause of overheating is the accumulation of dust inside the
15 electronic device. The electrical components in the device can generate heat and any fans inside the device can help move the air to keep the components cooled to normal operating temperatures. Inadequate cooling can cause excess heat to build up inside the device which can damage components.

[0013] Heat buildup can cause problems for any electronic device. Generally,
20 when temperatures inside the device rises above about 35°C, the risk of damaging important internal components can increase greatly.

[0014] Accordingly, a need exists for a heat dissipation coating composition for electronic devices that can absorb/spread heat such that overheating of electronic devices is reduced or eliminated.

25 [0015] "Electronic device(s)" as described herein is/are not limited to and can include desktop computers, laptop computers, mobile phones, handheld devices, and printing devices.

[0016] As used herein, "(s)" at the end of some terms indicates that those
30 terms/phrases may be singular in some examples or plural in some examples. It is to be understood that the terms without "(s)" may be also be used singularly or plurally in many examples.

[0017] "Heat Dissipation," as used herein, refers to a composition that can absorb and/or distribute heat to thereby reduce heat emanating from any electronic device hot spots.

[0018] In some examples, described herein is a heat dissipation coating composition for an electronic device comprising: a transparent coating layer deposited on a surface of the electronic device, wherein the coating layer comprises: a heat absorber selected from the group consisting of silica aerogel, carbon nanotubes, carbon nanotube aerogel, graphene, graphene aerogel, and combinations thereof, a transparent resin selected from the group consisting of a polyacrylic resin, a polycarbonate resin, a cyclic olefin resin, an epoxy resin, a urethane resin, a silicone resin, a cyanoacrylate resin, a polyester resin, and combinations thereof, and a solvent; and a heat spreader layer deposited at least partially on top of the transparent coating layer or deposited on the surface of the electronic device adjacent to the transparent coating layer, wherein the heat spreader layer comprises: metallic or non-metallic particles selected from the group consisting of copper, aluminum, graphite, carbon nanotube, graphene on a metal, graphene, and combinations thereof.

[0019] In some examples, the transparent coating layer fully coats the surface of the electronic device.

[0020] In some examples, the transparent coating layer fully coating the surface of the electronic device has a thickness of about 1 μm to about 100 μm , or from about 5 μm to about 75 μm , or from about 10 μm to about 50 μm .

[0021] In some examples, the heat absorber is present in the transparent coating layer in an amount of from about 10 wt% to about 70 wt% based on the total weight of the transparent coating layer, or from about 15 wt% to about 60 wt% based on the total weight of the transparent coating layer, or from about 20 wt% to about 50 wt% based on the total weight of the transparent coating layer, or less than about 70 wt% based on the total weight of the transparent coating layer, or less than about 60 wt% based on the total weight of the transparent coating layer, or less than about 50 wt% based on the total weight of the transparent coating layer, or less than about 40 wt% based on the total weight of the transparent coating layer, or at least about 10 wt% based on the total weight of the transparent coating layer, or at least about 20 wt% based on the total weight of the transparent

coating layer, or at least about 30 wt% based on the total weight of the transparent coating layer, or at least about 40 wt% based on the total weight of the transparent coating layer, or at least about 50 wt% based on the total weight of the transparent coating layer.

5 [0022] In some examples, the transparent resin is present in the transparent coating layer in an amount of from about 5 wt% to about 50 wt% based on the total weight of the transparent coating layer, or from about 10 wt% to about 45 wt% based on the total weight of the transparent coating layer, from about 15 wt% to about 40 wt% based on the total weight of the transparent coating layer, or from
10 about 20 wt% to about 35 wt% based on the total weight of the transparent coating layer, or less than about 50 wt% based on the total weight of the transparent coating layer, or less than about 40 wt% based on the total weight of the transparent coating layer, or less than about 30 wt% based on the total weight of the transparent coating layer, or less than about 20 wt% based on the total weight
15 of the transparent coating layer, or at least about 5 wt% based on the total weight of the transparent coating layer, or at least about 10 wt% based on the total weight of the transparent coating layer, or at least about 15 wt% based on the total weight of the transparent coating layer, or at least about 20 wt% based on the total weight of the transparent coating layer, or at least about 25 wt% based on the total weight
20 of the transparent coating layer, or at least about 30 wt% based on the total weight of the transparent coating layer, or at least about 35 wt% based on the total weight of the transparent coating layer, or at least about 40 wt% based on the total weight of the transparent coating layer, or at least about 45 wt% based on the total weight of the transparent coating layer.

25 [0023] In some examples, the solvent is selected from the group consisting of ketone-based solvents, ester-based solvents, alcohol-based solvents, amide-based solvents, ether-based solvents, a hydrocarbon-based solvents, and combinations thereof.

[0024] In some examples, the heat spreader layer is deposited to coat 50% or
30 less of the top of the transparent coating layer.

[0025] In some examples, the heat spreader layer is deposited to coat at least 50% of the top of the transparent coating layer.

[0026] In some examples, the heat spreader layer is deposited on the surface of the electronic device adjacent to the transparent coating layer spreader layer to coat 50% or less of the surface of the electronic device.

5 [0027] In some examples, the heat spreader layer has a thickness of about 0.01 mm to about 0.5 mm, or from about 0.02 mm to about 0.4 mm, or from about 0.025 mm to about 0.3 mm.

[0028] In some examples, described is an electronic device comprising the heat dissipation coating composition described above.

10 [0029] In some examples, described herein is a method of depositing a heat dissipation coating composition on an electronic device comprising: depositing a transparent coating layer on a surface of the electronic device, wherein the coating layer comprises: a heat absorber selected from the group consisting of silica aerogel, carbon nanotubes, carbon nanotube aerogel, graphene, graphene aerogel, and combinations thereof, a transparent resin selected from the group
15 consisting of a polyacrylic resin, a polycarbonate resin, a cyclic olefin resin, an epoxy resin, a urethane resin, a silicone resin, a cyanoacrylate resin, a polyester resin, and combinations thereof, and a solvent; and depositing a heat spreader layer at least partially on top of the transparent coating layer or depositing the heat spreader layer on the surface of the electronic device adjacent to the transparent
20 coating layer, wherein the heat spreader layer comprises: metallic or non-metallic particles selected from the group consisting of copper, aluminum, graphite, graphene on a metal, carbon nanotube, graphene, and combinations thereof.

[0030] In some examples, the transparent coating layer fully coating the surface of the electronic device has a thickness of about 1 μm to about 100 μm , or from
25 about 5 μm to about 75 μm , or from about 10 μm to about 50 μm .

[0031] In some examples, the heat spreader layer has a thickness of about 0.01 mm to about 0.5 mm, or from about 0.02 mm to about 0.4 mm, or from about 0.025 mm to about 0.3 mm.

30 [0032] In some examples, the heat spreader layer is deposited to coat at least 90% of the top of the transparent coating layer, or to coat at least 91% of the top of the transparent coating layer, or to coat at least 92% of the top of the transparent coating layer, to coat at least 93% of the top of the transparent coating layer, or to coat at least 94% of the top of the transparent coating layer, or to coat at least 95%

of the top of the transparent coating layer, or to coat at least 96% of the top of the transparent coating layer, or to coat at least 97% of the top of the transparent coating layer, or to coat at least 98% of the top of the transparent coating layer, or to coat at least 99% of the top of the transparent coating layer, or to coat 100% of the top of the transparent coating layer.

[0033] Turning now to the figures:

[0034] FIG. 1 is a sectional view of an electronic device substrate coated with a heat dissipation coating composition according to an example. In FIG. 1, an electronic device 100 with hot spots 105 are shown. The hot spots in the electronic device can include but are not limited to the central processing unit (CPU) or an integrated circuit (IC) / printed circuit board (PCB). The heat 115 generated from the hot spots 105 can be absorbed by a transparent coating layer 130 and heat spreader layers 125 both of which are coated on top of a surface 120 of the electronic device. In this example, the surface 120 of the electronic device is on an opposite surface from the surface with the hot spots.

[0035] FIG. 2 is a sectional view of an electronic device substrate coated with a heat dissipation coating composition according to another example. In FIG. 2, an electronic device 100 with hot spots 105 are shown. The hot spots in the electronic device can include but are not limited to the CPU or an IC/PCB. The heat 115 generated from the hot spots 105 can be absorbed by a transparent coating layer 230 deposited on top of heat spreader layers 225 both of which are coated on top of a surface 220 of the electronic device. In this example, the surface 220 of the electronic device is on an opposite surface from the surface with the hot spots.

[0036] FIG. 3 is a sectional view of an electronic device substrate coated with a heat dissipation coating composition according to another example. In FIG. 3, an electronic device 100 with hot spots 105 are shown. The hot spots in the electronic device can include but are not limited to the CPU or an IC/PCB. The heat 115 generated from the hot spots 105 can be absorbed by a transparent coating layer 330 deposited on top of a surface 320 of the electronic device. Heat spreader layers 325 can be deposited on top of the transparent coating layer 330. In this example, the surface 320 of the electronic device is on an opposite surface from the surface with the hot spots.

[0037] FIG. 4 is a top view of an electronic device substrate coated with a heat dissipation coating composition according to an example. In FIG. 4, the top view of the examples shown in FIG. 1 and FIG. 2 is shown where the transparent coating layer 430 coats the surface 420 of the electronic device. The heat spreader layers 425 are directly coated on top of the surface 420 of the electronic device.

[0038] FIG. 5 is a top view of an electronic device substrate coated with a heat dissipation coating composition according to an example. In FIG. 5, the top view of the example shown in FIG. 3 is shown where the transparent coating layer 530 coats the surface 520 of the electronic device. The heat spreader layers 525 are coated on top of the transparent coating layer 530.

[0039] It is to be understood that the configurations described in FIGS. 1- 5 can be modified without affecting the functioning of the described heat dissipation coating composition. For example, the hot spots, the transparent coating layer, and the heat spreader layer can be all on the same surface.

[0040] FIG. 6 is a top view of a common synthetic graphite film 635. This commonly used synthetic graphite film has heat dissipation properties but this film is commonly black in color. The use of this layer results in production of an electronic device that has a black surface color. This can be limiting and not a target for many electronic devices. Further, the surface area of the synthetic graphite film is limited to the available area of the electronic device on which the film can be applied. In contrast with this common black colored synthetic graphite film, the heat dissipation coating composition described herein include transparent coating layers, which can allow for wide use across many different applications of electronic devices. Further, the surface area of the transparent coating layer is higher than the common synthetic graphite film due to the presence of silica nanoparticles in aerogel, carbon nanotubes, carbon nanotubes in aerogel, graphene nanoparticles, and combinations thereof.

[0041] In some examples, the size of the silica nanoparticles, carbon nanotubes, carbon, and graphene nanoparticles in the transparent coating layer is from about 1 nm to about 800 nm, or from about 10 nm to about 500 nm, or from about 20 nm to about 100 nm, or from about 30 nm to about 80 nm, or at least about 1 nm, or at least about 10 nm, or at least about 50 nm, or at least about 100 nm, or at least about 150 nm, or at least about 200 nm, or at least about 500 nm, or at least about

800 nm, or less than about 1000 nm, or less than about 800 nm, or less than about 500 nm, or less than about 400 nm, or less than about 300 nm, or less than about 200 nm, or less than about 100 nm, or less than about 90 nm, or less than about 80 nm, or less than about 70 nm, or less than about 60 nm, or less than about 50 nm,
5 or less than about 40 nm, or less than about 30 nm, or less than about 20 nm, or less than about 10 nm, or less than about 5 nm, or less than about 3-4 nm.

[0042] In some examples, the amount of the silica nanoparticles, carbon nanotubes, carbon, and graphene nanoparticles in the transparent coating layer is from about 1 wt% to about 70 wt% based on the total weight of the transparent
10 coating layer, or from about 5 wt% to about 60 wt% based on the total weight of the transparent coating layer, or from about 10 wt% to about 50 wt% based on the total weight of the transparent coating layer, or from about 15 wt% to about 45 wt% based on the total weight of the transparent coating layer, or from about 20 wt% to about 40 wt% based on the total weight of the transparent coating layer, or at least
15 about 1 wt% based on the total weight of the transparent coating layer, or at least about 10 wt% based on the total weight of the transparent coating layer, or at least about 20 wt% based on the total weight of the transparent coating layer, or at least about 30 wt% based on the total weight of the transparent coating layer, or at least about 40 wt% based on the total weight of the transparent coating layer, or at least
20 about 50 wt% based on the total weight of the transparent coating layer, or at least about 60 wt% based on the total weight of the transparent coating layer, or at least about 70 wt% based on the total weight of the transparent coating layer, or less than about 85 wt% based on the total weight of the transparent coating layer, or less than about 75 wt% based on the total weight of the transparent coating layer,
25 or less than about 65 wt% based on the total weight of the transparent coating layer, or less than about 55 wt% based on the total weight of the transparent coating layer, or less than about 45 wt% based on the total weight of the transparent coating layer, or less than about 35 wt% based on the total weight of the transparent coating layer, or less than about 25 wt% based on the total weight
30 of the transparent coating layer, or less than about 15 wt% based on the total weight of the transparent coating layer.

[0043] In some examples, carbon nanotubes can have high surface areas (e.g., greater than about 1,085 m²/g), which can contribute to thermal radiation

absorption/spreading in the transparent coating layer compared to a common synthetic graphite film or other similar common film.

[0044] FIG. 7 is a top view of a transparent coating layer 730 in a heat dissipation coating composition according to an example. The transparent coating layer 730 includes carbon nanotubes of various shapes.

[0045] FIG. 8 is a flow diagram of a method of depositing a heat dissipation coating composition on an electronic device according to an example. The method can include depositing a transparent coating layer on a surface of the electronic device 810 and depositing a heat spreader layer at least partially on top of the transparent coating layer or depositing the heat spreader layer on the surface of the electronic device adjacent to the transparent coating layer 820.

[0046] In some examples, described herein is a heat dissipation coating composition for an electronic device comprising: a transparent coating layer deposited on a surface of the electronic device, wherein the coating layer comprises: a heat absorber selected from the group consisting of silica aerogel, carbon nanotubes, carbon nanotube aerogel, graphene, graphene aerogel, and combinations thereof, a transparent resin selected from the group consisting of a polyacrylic resin, a polycarbonate resin, a cyclic olefin resin, an epoxy resin, a urethane resin, a silicone resin, a cyanoacrylate resin, a polyester resin, and combinations thereof, and a solvent; and a heat spreader layer deposited at least partially on top of the transparent coating layer or deposited on the surface of the electronic device adjacent to the transparent coating layer, wherein the heat spreader layer comprises: metallic or non-metallic particles selected from the group consisting of copper, aluminum, graphite, graphene on a metal, carbon nanotube, graphene, and combinations thereof.

[0047] In some examples, the transparent coating layer can comprise: a heat absorber selected from the group consisting of silica aerogel, carbon nanotubes, carbon nanotube aerogel, graphene, graphene aerogel, and combinations thereof; a transparent resin selected from the group consisting of a polyacrylic resin, a polycarbonate resin, a cyclic olefin resin, an epoxy resin, a urethane resin, a silicone resin, a cyanoacrylate resin, a polyester resin, and combinations thereof; and a solvent.

[0048] In some examples, the thermal radiation coefficient of the transparent coating layer is in the range of 0.9-0.98.

[0049] In some examples, the heat absorber is present in the transparent coating layer in an amount of from about 10 wt% to about 70 wt% based on the total weight of the transparent coating layer, or from about 15 wt% to about 60 wt% based on the total weight of the transparent coating layer, or from about 20 wt% to about 50 wt% based on the total weight of the transparent coating layer, or less than about 70 wt% based on the total weight of the transparent coating layer, or less than about 60 wt% based on the total weight of the transparent coating layer, or less than about 50 wt% based on the total weight of the transparent coating layer, or less than about 40 wt% based on the total weight of the transparent coating layer, or at least about 10 wt% based on the total weight of the transparent coating layer, or at least about 20 wt% based on the total weight of the transparent coating layer, or at least about 30 wt% based on the total weight of the transparent coating layer, or at least about 40 wt% based on the total weight of the transparent coating layer, or at least about 50 wt% based on the total weight of the transparent coating layer.

[0050] In some examples, the transparent resin is present in the transparent coating layer in an amount of from about 5 wt% to about 50 wt% based on the total weight of the transparent coating layer, or from about 10 wt% to about 45 wt% based on the total weight of the transparent coating layer, from about 15 wt% to about 40 wt% based on the total weight of the transparent coating layer, or from about 20 wt% to about 35 wt% based on the total weight of the transparent coating layer, or less than about 50 wt% based on the total weight of the transparent coating layer, or less than about 40 wt% based on the total weight of the transparent coating layer, or less than about 30 wt% based on the total weight of the transparent coating layer, or less than about 20 wt% based on the total weight of the transparent coating layer, or at least about 5 wt% based on the total weight of the transparent coating layer, or at least about 10 wt% based on the total weight of the transparent coating layer, or at least about 15 wt% based on the total weight of the transparent coating layer, or at least about 20 wt% based on the total weight of the transparent coating layer, or at least about 25 wt% based on the total weight of the transparent coating layer, or at least about 30 wt% based on the total weight

of the transparent coating layer, or at least about 35 wt% based on the total weight of the transparent coating layer, or at least about 40 wt% based on the total weight of the transparent coating layer, or at least about 45 wt% based on the total weight of the transparent coating layer.

5 [0051] In some examples, the solvent is selected from the group consisting of ketone-based solvents, ester-based solvents, alcohol-based solvents, amide-based solvents, ether-based solvents, a hydrocarbon-based solvents, and combinations thereof. The solvent is present in the transparent coating layer in an amount of from about 10 wt% to about 70 wt% based on the total weight of the transparent
10 coating layer, or from about 20 wt% to about 60 wt% based on the total weight of the transparent coating layer, or from about 30 wt% to about 50 wt% based on the total weight of the transparent coating layer, or less than about 70 wt% based on the total weight of the transparent coating layer, or less than about 60 wt% based on the total weight of the transparent coating layer, or less than about 50 wt%
15 based on the total weight of the transparent coating layer, or less than about 40 wt% based on the total weight of the transparent coating layer, or less than about 30 wt% based on the total weight of the transparent coating layer, or less than about 20 wt% based on the total weight of the transparent coating layer, or at least about 10 wt% based on the total weight of the transparent coating layer, or at least
20 about 20 wt% based on the total weight of the transparent coating layer, or at least about 30 wt% based on the total weight of the transparent coating layer, or at least about 40 wt% based on the total weight of the transparent coating layer, or at least about 50 wt% based on the total weight of the transparent coating layer, or at least about 60 wt% based on the total weight of the transparent coating layer, or at least
25 about 70 wt% based on the total weight of the transparent coating layer.

[0052] In some examples, the transparent coating layer can include plasticizer(s), flow promoter(s), surfactant(s), release agent(s), flattening agent(s), coloring agent(s), wetting agent(s), wax ingredient(s), silicone based polymer ingredient(s) (e.g., polydimethylsiloxane (PDMS)), matting agent(s), co-solvent(s),
30 or combinations thereof.

[0053] In some examples, the heat spreader layer can comprise: metallic or non-metallic particles selected from the group consisting of copper, aluminum,

graphite, graphene on a metal, carbon nanotube, graphene, and combinations thereof.

[0054] In some examples, the heat spreader layer can include the transparent resin and the solvent described above for the transparent coating layer.

5 [0055] In some examples, the heat spreader layer can include a non-transparent resin and a solvent selected from the group consisting of ketone-based solvents, ester-based solvents, alcohol-based solvents, amide-based solvents, ether-based solvents, a hydrocarbon-based solvents, and combinations thereof. A non-transparent resin can include but is not limited to polyvinyl acetate or polyvinyl
10 chloride.

[0056] The heat spreader layer can further include plasticizer(s), flow promoter(s), surfactant(s), release agent(s), flattening agent(s), coloring agent(s), wetting agent(s), wax ingredient(s), silicone based polymer ingredient(s) (e.g., polydimethylsiloxane (PDMS)), matting agent(s), co-solvent(s), or combinations
15 thereof.

[0057] In some examples, described herein is a method of depositing a heat dissipation coating composition on an electronic device comprising: depositing a transparent coating layer on a surface of the electronic device, wherein the coating layer comprises: a heat absorber selected from the group consisting of silica
20 aerogel, carbon nanotubes, carbon nanotube aerogel, graphene, graphene aerogel, and combinations thereof, a transparent resin selected from the group consisting of a polyacrylic resin, a polycarbonate resin, a cyclic olefin resin, an epoxy resin, a urethane resin, a silicone resin, a cyanoacrylate resin, a polyester resin, and combinations thereof, and a solvent; and depositing a heat spreader
25 layer at least partially on top of the transparent coating layer or depositing the heat spreader layer on the surface of the electronic device adjacent to the transparent coating layer, wherein the heat spreader layer comprises: metallic or non-metallic particles selected from the group consisting of copper, aluminum, graphite, graphene on a metal, carbon nanotube, graphene, and combinations thereof.

30 [0058] The methods of depositing the transparent coating layer and the heat spreader layer can include but are not limited to gas phase methods and application methods, and the gas phase methods include physical methods such as a vacuum deposition method, sputtering method and the like, and chemical

methods such as a chemical vapor deposition (CVD) method and the like, and the application methods include a roll coat method, gravure coat method, slide coat method, spray method, immersion method and screen printing method, and the like.

5 [0059] Some benefits of the heat dissipation coating composition described herein can include but are not limited to achieving reduced electronic device temperatures, extending lifetime of electronic device components as a result of heat dissipation, increasing thermal radiation dissipation compared to graphite film or graphene film due to high surface area of silica nanoparticles, carbon
10 nanotubes, carbon, and graphene nanoparticles, resolving or reducing electronic device hot spot issues, reducing the risk of battery explosion due to electronic device overheating, preventing or reducing user injury due to hot spots, achieving reduction or elimination of hot spots thereby allowing fan-less electronic devices, improving information loading speed and power efficiency, applying the heat
15 dissipation coating composition allows heat dissipation in irregularly shaped electronic device, and combinations thereof.

[0060] Unless otherwise stated, any feature described hereinabove can be combined with any example or any other feature described herein.

[0061] In describing and claiming the examples disclosed herein, the singular
20 forms “a,” “an,” and “the” include plural referents unless the context clearly dictates otherwise.

[0062] It is to be understood that concentrations, amounts, and other numerical data may be expressed or presented herein in range formats. It is to be understood that such range formats are used merely for convenience and brevity
25 and thus should be interpreted flexibly to include not just the numerical values explicitly recited as the end points of the range, but also to include all the individual numerical values or sub-ranges encompassed within that range as if each numerical value and sub-range is explicitly recited. As an illustration, a numerical range of “about 1 wt% to about 5 wt%” should be interpreted to include not just the
30 explicitly recited values of about 1 wt% to about 5 wt%, but also include individual values and subranges within the indicated range. Thus, included in this numerical range are individual values such as 2, 3.5, and 4 and sub-ranges such as from 1-3,

from 2-4, and from 3-5, *etc.* This same applies to ranges reciting a single numerical value.

[0063] Reference throughout the specification to “one example,” “some examples,” “another example,” “an example,” and so forth, means that a particular
5 element (*e.g.*, feature, structure, and/or characteristic) described in connection with the example is included in at least one example described herein, and may or may not be present in other examples. In addition, it is to be understood that the described elements for any example may be combined in any suitable manner in the various examples unless the context clearly dictates otherwise.

10 [0064] Unless otherwise stated, references herein to “wt%” of a component are to the weight of that component as a percentage of the whole composition comprising that component. For example, references herein to “wt%” of, for example, a solid material such as polyurethane(s) or colorant(s) dispersed in a liquid composition are to the weight percentage of those solids in the composition,
15 and not to the amount of that solid as a percentage of the total non-volatile solids of the composition.

[0065] If a standard test is mentioned herein, unless otherwise stated, the version of the test to be referred to is the most recent at the time of filing this patent application.

20 [0066] All amounts disclosed herein and in the examples below are in wt% unless indicated otherwise.

[0067] While several examples have been described in detail, it is to be understood that the disclosed examples may be modified. Therefore, the foregoing description is to be considered non-limiting.

25

CLAIMS

What is claimed is:

- 5 1. A heat dissipation coating composition for an electronic device comprising:
a transparent coating layer deposited on a surface of the electronic device,
wherein the coating layer comprises:
- 10 a heat absorber selected from the group consisting of silica aerogel,
carbon nanotubes, carbon nanotube aerogel, graphene, graphene aerogel, and
combinations thereof,
- a transparent resin selected from the group consisting of a polyacrylic
resin, a polycarbonate resin, a cyclic olefin resin, an epoxy resin, a urethane
resin, a silicone resin, a cyanoacrylate resin, a polyester resin, and
combinations thereof, and
- 15 a solvent; and
- a heat spreader layer deposited at least partially on top of the transparent
coating layer or deposited on the surface of the electronic device adjacent to the
transparent coating layer, wherein the heat spreader layer comprises:
- 20 metallic or non-metallic particles selected from the group consisting of
copper, aluminum, graphite, carbon nanotube, graphene on a metal, graphene,
and combinations thereof.
2. The heat dissipation coating composition of claim 1, wherein the transparent
coating layer fully coats the surface of the electronic device.
- 25 3. The heat dissipation coating composition of claim 2, wherein the transparent
coating layer fully coating the surface of the electronic device has a thickness of about
1 μm to about 100 μm .

4. The heat dissipation coating composition of claim 1, wherein the heat absorber is present in the transparent coating layer in an amount of from about 10 wt% to about 70 wt% based on the total weight of the transparent coating layer.

5 5. The heat dissipation coating composition of claim 1, wherein the transparent resin is present in the transparent coating layer in an amount of from about 5 wt% to about 50 wt% based on the total weight of the transparent coating layer.

10 6. The heat dissipation coating composition of claim 1, wherein the solvent is selected from the group consisting of ketone-based solvents, ester-based solvents, alcohol-based solvents, amide-based solvents, ether-based solvents, a hydrocarbon-based solvents, and combinations thereof.

15 7. The heat dissipation coating composition of claim 1, wherein the heat spreader layer is deposited to coat 50% or less of the top of the transparent coating layer.

20 8. The heat dissipation coating composition of claim 1, wherein the heat spreader layer is deposited to coat at least 50% of the top of the transparent coating layer.

25 9. The heat dissipation coating composition of claim 1, wherein the heat spreader layer is deposited on the surface of the electronic device adjacent to the transparent coating layer spreader layer to coat 50% or less of the surface of the electronic device.

10. The heat dissipation coating composition of claim 1, wherein the heat spreader layer has a thickness of about 0.01 mm to about 0.5 mm.

30 11. An electronic device comprising the heat dissipation coating composition of claim 1.

12. A method of depositing a heat dissipation coating composition on an electronic device comprising:

depositing a transparent coating layer on a surface of the electronic device,

5 wherein the coating layer comprises:

a heat absorber selected from the group consisting of silica aerogel, carbon nanotubes, carbon nanotube aerogel, graphene, graphene aerogel, and combinations thereof,

10 a transparent resin selected from the group consisting of a polyacrylic resin, a polycarbonate resin, a cyclic olefin resin, an epoxy resin, a urethane resin, a silicone resin, a cyanoacrylate resin, a polyester resin, and combinations thereof, and

a solvent; and

15 depositing a heat spreader layer at least partially on top of the transparent coating layer or depositing the heat spreader layer on the surface of the electronic device adjacent to the transparent coating layer, wherein the heat spreader layer comprises:

20 metallic or non-metallic particles selected from the group consisting of copper, aluminum, graphite, carbon nanotube, graphene on a metal, graphene, and combinations thereof.

13. The method of depositing a heat dissipation coating composition of claim 12, wherein the transparent coating layer fully coating the surface of the electronic device has a thickness of about 1 μm to about 100 μm .

25

14. The method of depositing a heat dissipation coating composition of claim 12, wherein the heat spreader layer has a thickness of about 0.01 mm to about 0.5 mm.

15. The method of depositing a heat dissipation coating composition of claim 12, wherein the heat spreader layer is deposited to coat at least 90% of the top of the transparent coating layer.

5

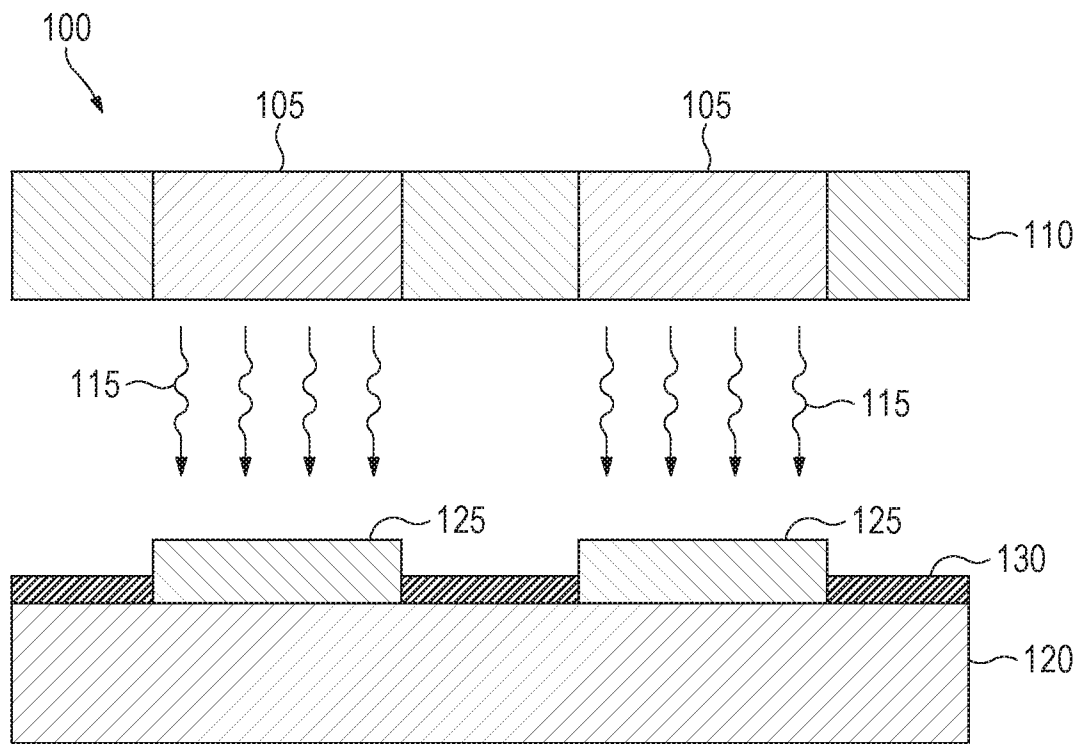


FIG. 1

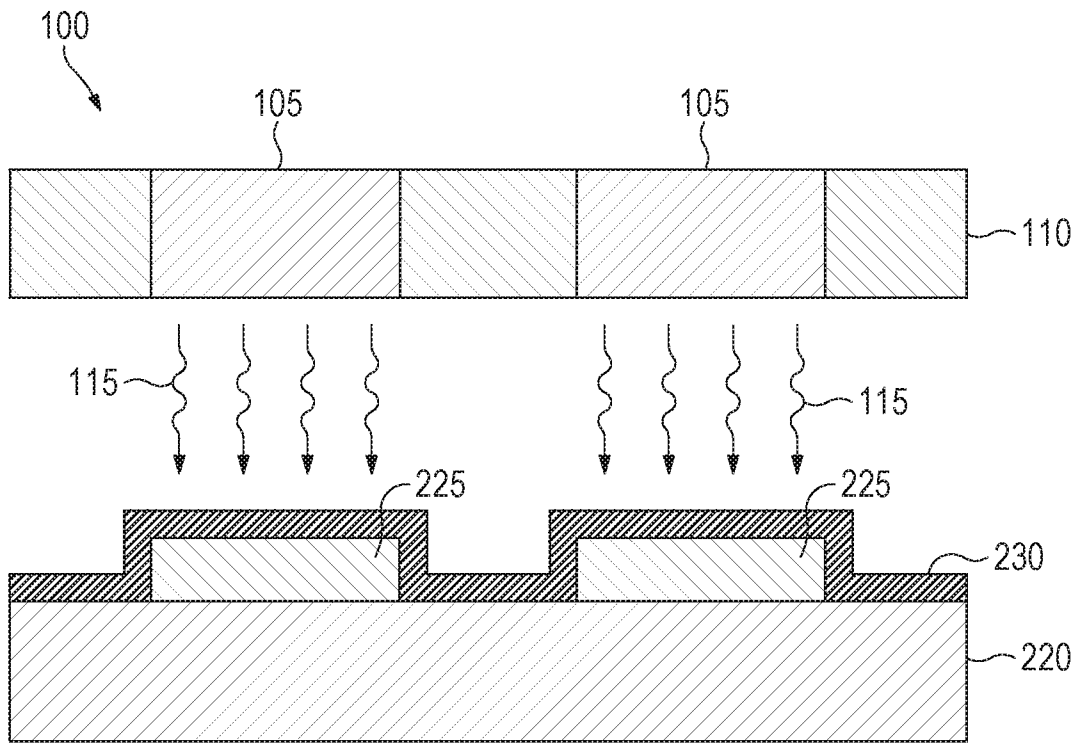


FIG. 2

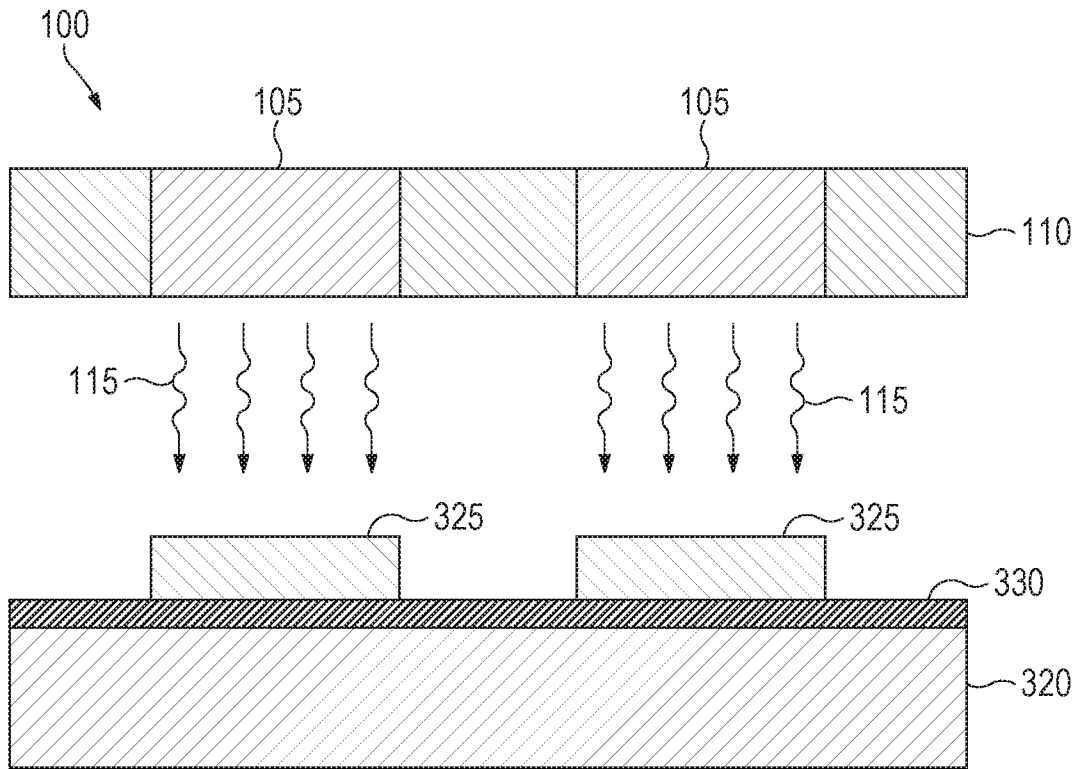


FIG. 3

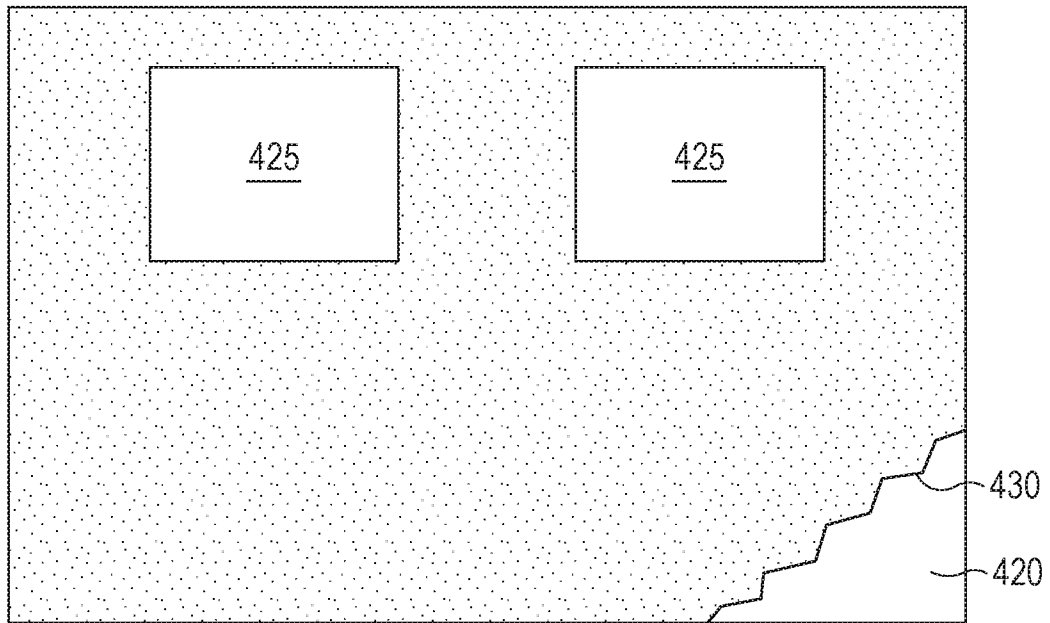


FIG. 4

5/8

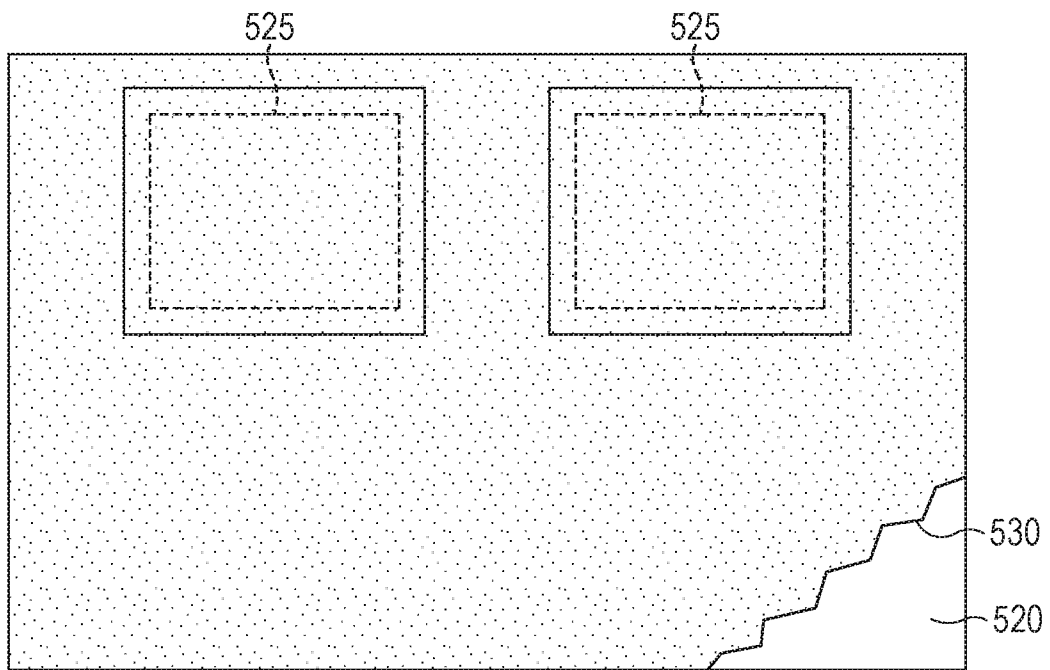


FIG. 5

6/8

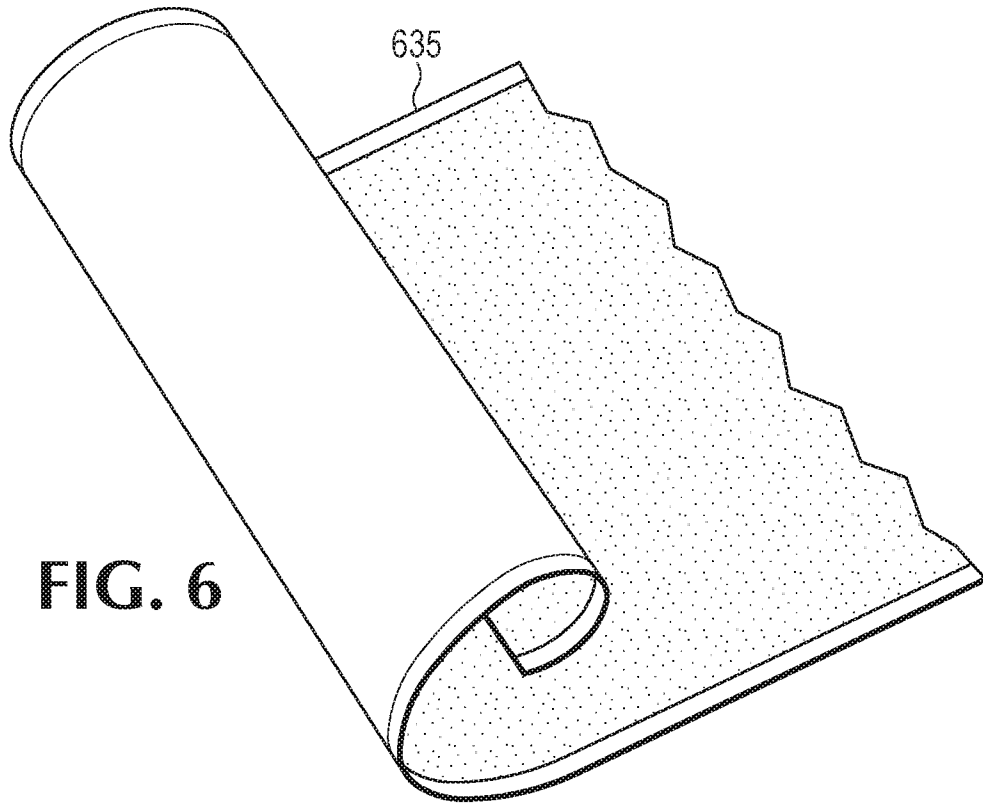


FIG. 6

7/8

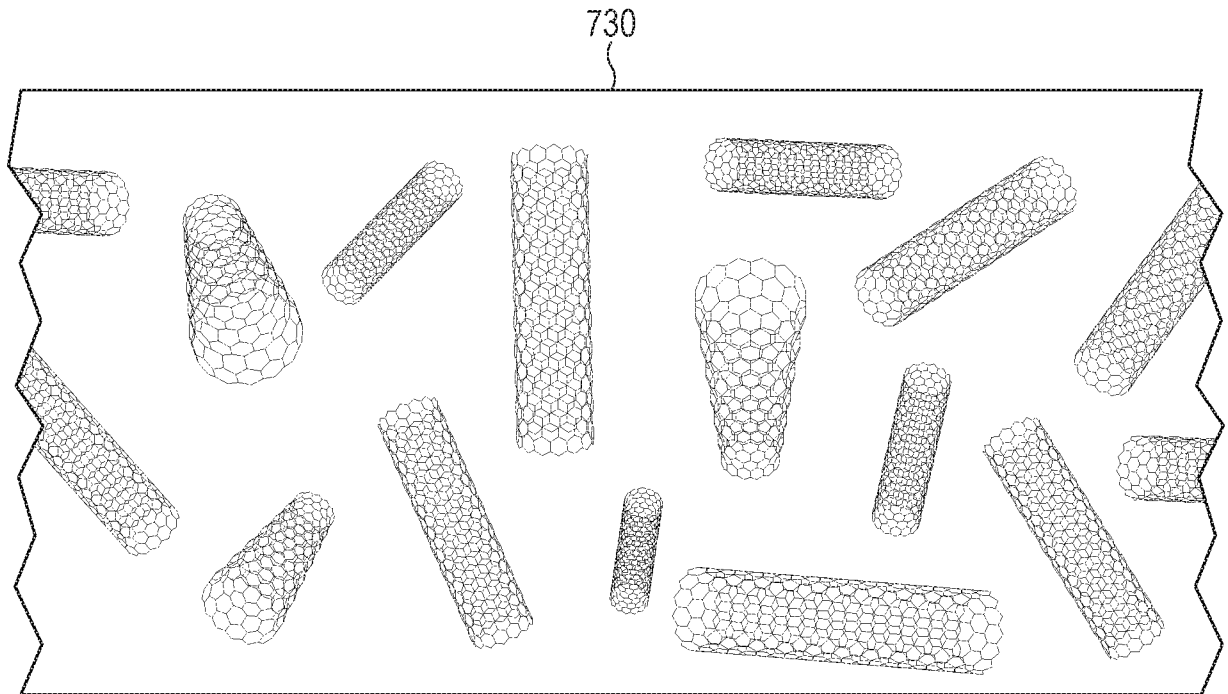
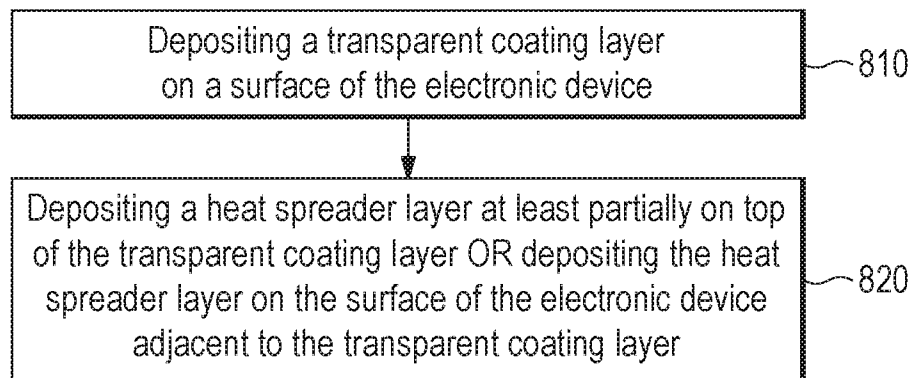


FIG. 7

8/8

**FIG. 8**

INTERNATIONAL SEARCH REPORT

International application No.

PCT/US 2017/041857

A. CLASSIFICATION OF SUBJECT MATTER

C09K5/00 (2006.01)

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

C09K 5/00, C09D 1/00, 5/00, H05K 7/20

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

PatSearch, Espacenet, WIPO, USPTO, Google

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	TW 201604248 A (LIN LIAN-XIN) 01.02.2016, abstract, paragraph [0017]	1-15
Y	WO 2017/018999 (HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P.) 02.02.2017, claims	1-15
Y	JP S62216979 A (SUMITOMO ELECTRIC IND LTD) 24.09.1987, claims	1-15
A	CN 102850911 A (ZHEJIANG SCI-TECH UNIVERSITY) 02.01.2013, abstract	1-15
A	JP H02207555 A (MITSUBISHI METAL CORP et al.) 17.08.1990, abstract	1-15

 Further documents are listed in the continuation of Box C. See patent family annex.

* Special categories of cited documents:	“T” later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
“A” document defining the general state of the art which is not considered to be of particular relevance	“X” document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone
“E” earlier document but published on or after the international filing date	“Y” document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art
“L” document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)	“&” document member of the same patent family
“O” document referring to an oral disclosure, use, exhibition or other means	
“P” document published prior to the international filing date but later than the priority date claimed	

Date of the actual completion of the international search

06 April 2018 (06.04.2018)

Date of mailing of the international search report

17 May 2018 (17.05.2018)

Name and mailing address of the ISA/RU:
Federal Institute of Industrial Property,
Berezhkovskaya nab., 30-1, Moscow, G-59,
GSP-3, Russia, 125993
Facsimile No: (8-495) 531-63-18, (8-499) 243-33-37

Authorized officer

I.Doroshenko

Telephone No. (8-495) 531-65-15